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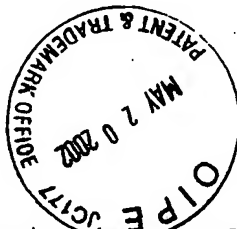
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Applicant:	Hubert DE STEUR et al.	Case No.:	32860-000291/US
Serial No.:	10/079,896	Filing Date:	December 27, 2001

Title: METHOD AND APPARATUS FOR STRUCTURING PRINTED CIRCUIT
BOARDS

Please acknowledge receipt of: Letter Claiming Priority, Priority
document Number 110 27 357.6



By stamping and returning to Harness, Dickey & Pierce, P.L.C.

USPTO Date Stamp

Due: N/A

Attorney: DJD - May 20, 2002

⑥



PATENT
32860-000291/US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Hubert DE STEUR et al.
Application No.: 10/076,896
Filed: December 27, 2001
For: METHOD AND APPARATUS FOR STRUCTURING PRINTED
CIRCUIT BOARDS

PRIORITY LETTER

May 20, 2002

Honorable Commissioner of Patents and Trademarks
Washington, DC 20231

Dear Sirs:

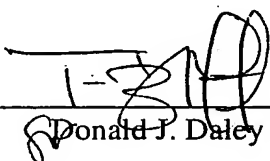
Pursuant to the provisions of 35 U.S.C. 119, enclosed is/are a certified copy of the following priority document(s).

<u>Application No.</u>	<u>Date Filed</u>	<u>Country</u>
101 27 357.6	6 June 2001	Germany

In support of Applicant's priority claim, please enter this document into the file.

Respectfully submitted,

HARNESS, DICKEY, & PIERCE, P.L.C.

By  # 46,175
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BUNDESREPUBLIK DEUTSCHLAND



"Method and Apparatus
for Structuring Printed
Circuit Boards."
10/079,896

Prioritätsbescheinigung über die Einreichung einer Patentanmeldung

Aktenzeichen: 101 27 357.6

Anmeldetag: 6. Juni 2001

Anmelder/Inhaber: Siemens Dematic AG, Nürnberg/DE

Bezeichnung: Verfahren und Einrichtung zur Strukturierung
von Leiterplatten

IPC: H 05 K 3/02

Die angehefteten Stücke sind eine richtige und genaue Wiedergabe der
ursprünglichen Unterlagen dieser Patentanmeldung.

München, den 4. März 2002
Deutsches Patent- und Markenamt
Der Präsident
Im Auftrag

Waliner